

**IN THE UNITED STATES PATENT  
AND TRADEMARK OFFICE**

-- PATENT --

Applicant: Lunde, Aron T. Docket No.: 37829.0400  
Serial No.: To Be Assigned Group Art Unit: To Be Assigned  
Filing Date: Examiner: To Be Assigned  
Title: A DIE ASSEMBLY AND METHOD FOR FORMING A DIE ON A WAFER

**DECLARATION FOR PATENT APPLICATION**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled **A DIE ASSEMBLY AND METHOD FOR FORMING A DIE ON A WAFER**, the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with 37 C.F.R. §1.56.

I hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below, and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed.

Priority Not Claimed

[ ]

Number	Country	Filing Date
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I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below.

Application Number	Filing Date
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I hereby claim the benefit under 35 U.S.C. §120 of any United States application(s), or §365(c) of any PCT International application designating the United States, listed below and, 37829.0400\HENSCHD\PHX\1104307.

-1-

S&W Docket No. 37829.0400  
Micron No. 01-0596

insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of 35 U.S.C. §112, I acknowledge the duty to disclose material information as defined in 37 C.F.R. §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

Application Number	Filing Date	Status (Patent, Pending, Abandoned)
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

In the event that the Application Number and/or filing date is not available when this Declaration is executed, I hereby authorize and request any attorney associated with Snell & Wilmer, L.L.P., Customer No. 20322, to insert above the filing date and/or the application number of said application when known.

Full name of first inventor: Aron T. Lunde

Inventor's signature: Aron T. Lunde Date: 1/9/02

Residence Address: 2226 E. Skipperling Lane

City/State: Boise, Idaho Zip Code: 83706

Citizenship: USA

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AND TRADEMARK OFFICE**

**PATENT**

Applicant: Lunde, Aron T. Docket No.: 37829.0400  
Serial No.: To Be Assigned Group Art Unit: To Be Assigned  
Filing Date: 1/22/02 Examiner: To Be Assigned  
Title: A DIE ASSEMBLY AND METHOD FOR  
FORMING A DIE ON A WAFER

**POWER OF ATTORNEY**

Micron Technology, Inc., the Assignee of the entire right, title, and interest in and to the above-captioned United States patent application and all inventions disclosed and claimed therein, hereby appoints as its attorneys to prosecute the above-captioned United States patent application and to transact all business in the United States Patent and Trademark Office connected therewith and with the resulting patent, individually and collectively:

**SNELL & WILMER L.L.P.**  
One Arizona Center  
400 East Van Buren  
Phoenix, Arizona 85004-2202  
Telephone: (602) 382-6000  
Facsimile: (602) 382-6070

and the registered attorneys associated with Snell & Wilmer's Customer Number 020322 and also the following Micron attorneys: Michael L. Lynch, Reg. No. 30,871 and Charles Brantley, Reg. No. 38,086.

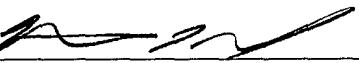
In the event that the Application Number and/or filing date is not available when this Power of Attorney is executed, the undersigned hereby authorizes and requests any attorney associated with Snell & Wilmer, L.L.P., Customer No. 20322, to insert above the filing date and/or the application number of said application when known.

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S&W Docket No. 37829.0400  
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Please send all further correspondence to Deborah Henschied at the above address.

By: Michael L. Lynch

Signature: 

Date: 1-10-2002